



ATTORNEY DOCKET NO. 43876-048
PATENT

#12/B
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IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re Application of:)

Paul Poenisch et al.)

Serial No.: 08/478,114)

Filed: June 7, 1995)

For: LOW COST, HIGH PERFORMANCE)
FLIP-CHIP BONDING TECHNIQUE)

Group Art Unit: 1107

Examiner: D. E. GRAYBILL

AMENDMENT UNDER 37 C.F.R. § 1.115

Hon. Commissioner of Patents
and Trademarks
Washington, D.C. 20231

SEP 18 1997
GROUP 1100

Sir:

In response to the Office Action dated March 24, 1997, having a shortened statutory period for response set to expire on June 24, 1997, a petition for a two-month extension of time up to and including August 24, 1997 being filed concurrently herewith, please amend the above-identified application as follows:

IN THE CLAIMS:

Please cancel claims 32-54, without prejudice, and amend claims 3, 5, 9, 18, 20, 27 and 30 as follows:

3. (Amended) The method of claim 1, wherein said gold bump comprises at least about 90 weight % Au, said barrier layer comprises at least about 90 weight % Ni, and said bronzing agent [comprises] is about 100 weight % Pb.